

# Digital Plate making conditions



## AFP TOP type

### Laser parameter

Resolution		2540dpi	4000dpi	4000dpi		
CDI mode		Round Top	Round Top	Flat Top		
Laser Energy		3.9J/sqcm	3.8J/sqcm	3.7J/sqcm		
Linearization	Cal	0.46	0.46	0.45		
	1.7D	1.70	1.70	1.70		
	0.3D	0.29	0.30	0.30		
Boost value	Microscreen	-	-	210		
	Groovy	-	-	210		
Main UV exposure		Inline UV1	Tube UV	Inline UV1	Tube UV	Inline UV2
Bump 1 to X (%)	45lpi/18lpc	2	2	2	2	2
	65lpi/26lpc	2	2	2	2	2
	85lpi/34lpc	2	3	2	2	2
	100lpi/40lpc	3	3	3	3	2
	120lpi/48lpc	4	5	4	3	2
	133lpi/52lpc	5	5	4	3	2
	150lpi/60lpc	6	6	5	5	2
	175lpi/69lpc	8	7	7	6	2

### Main UV parameter

UV mode	AFP1216EHQ	CDI Inline UV1	CDI Inline UV2
UV Main Exposure	4000mJ	600sec	910sec
UV Main Energy	-	22mW/sqcm	22mW/sqcm
Speed	-	-	7rotation
Dot fail test result	-	-	20pixel
Oxygen	-	-	-

### Back-flash exposure amount

Exposure	AFP1216EHQ							
Target RD	0.45mm	0.50mm	0.60mm	0.70mm	0.8mm	0.90mm	1.10mm	1.30mm
Back-flash amount (mJ)	1.14mm(045)	860	690	520	330	240	-	-
	1.70mm(067)	760	690	590	460	330	240	-
	2.54mm(100)	-	-	-	-	-	-	-
	2.84mm(112)	-	-	-	-	-	-	-

### Washout conditions

Processor / Solvent	AFP1321DP / SOLVIT							
Target RD	0.45mm	0.50mm	0.60mm	0.70mm	0.80mm	0.90mm	1.10mm	1.30mm
Washout speed (mm/min)	1.14mm(045)	270	260	200	170	140	-	-
	1.70mm(067)	260	250	210	190	150	140	-
	2.54mm(100)	-	-	-	-	-	-	-
	2.84mm(112)	-	-	-	-	-	-	-
Solvent Temp.	30degree C				86degree F			

### Drying conditions

Dryer	AFP1216D	
Temp.	53degree C	127degree F
Time	2hr	

### Post exposure & Light finishing exposure amount

Exposure	AFP1216LE
UVA	1000mJ
UVC	2000mJ Maximum